

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
MAGNI ET AL.

Serial No. **Not yet assigned**

Filing Date: **Herewith**

For: **MANUFACTURING METHOD OF AN
ELECTRONIC DEVICE PACKAGE**

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) APPLICATIONS, ASST. COMMISSIONER FOR PATENTS,
) WASHINGTON DC 20231-0001.
) EXPRESS MAIL NO: EL 768140226 US
) DATE OF DEPOSIT: December 26, 2001
) NAME: DAWN KIMLER
) SIGNATURE: Dawn Kimler

PRELIMINARY AMENDMENT

Director, U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Prior to the calculation of fees and examination of
the present application, please enter the amendments and
remarks set out below.

In the Drawings:

Submitted herewith is a request for proposed drawing
modifications as indicated in red ink to label FIGS. 1-6 as
prior art, to draw a line for reference number 13 in FIG. 7
and to label reference number 13 in FIG. 8.

In the Claims:

Please cancel Claims 1 to 7.

Please add new Claims 8 to 25.

8. A method for forming a plastic protective
package for an integrated circuit, the integrated circuit
being at least partially activated from outside of the
protective package, the method comprising:

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positioning a mold adjacent the integrated circuit, the mold comprising a half-mold having an insert projecting towards the inside of the mold, the insert being elastically deformable and abutting in pressing contact against at least one portion of the integrated circuit; and injecting a resin into the mold so that the protective package has a hole aligned with the at least one portion of the integrated circuit.

9. A method according to Claim 8, further comprising supplying pressure to the insert.

10. A method according to Claim 9, wherein the pressure is supplied to a back face of the insert opposite the integrated circuit.

11. A method according to Claim 9, wherein the half-mold has an opening therein for connection to a pressure source.

12. A method according to Claim 8, wherein the at least one portion comprises a border portion of the integrated circuit.

13. A method according to Claim 8, wherein the insert comprises a cylindrical skirt connected to adjacent portions of the half-mold, and an end carried by the cylindrical skirt.

14. A method for forming a plastic protective package for an integrated circuit, the method comprising:

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positioning a mold adjacent the integrated circuit, the mold comprising a half-mold having an elastically deformable membrane projecting towards the inside of the mold; supplying pressure to urge the elastically deformable membrane into pressing contact against at least one portion of the integrated circuit; and injecting a resin into the mold so that the protective package has a hole aligned with the at least one portion of the integrated circuit.

15. A method according to Claim 14, wherein the pressure is supplied to a back face of the insert opposite the integrated circuit.

16. A method according to Claim 14, wherein the half-mold has an opening therein for connection to a pressure source.

17. A method according to Claim 14, wherein the at least one portion comprises a border portion of the integrated circuit.

18. A method according to Claim 14, wherein the elastically deformable membrane comprises a cylindrical skirt connected to adjacent portions of the half-mold, and an end carried by the cylindrical skirt.

19. A mold for molding a plastic protective package for encapsulating an integrated circuit that can be at least partially activated from outside of the protective package, the mold comprising:

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first and second half-molds which are laid onto each other to form a space for containing the integrated circuit; and

an elastically deformable insert connected to the first half-mold and projecting substantially towards the integrated circuit to abut in pressing contact against at least one portion of the integrated circuit during a molding phase.

20. A mold according to Claim 19, wherein the first half-mold has an opening therein for connection to a pressure source.

21. A mold according to Claim 19, wherein the at least one portion comprises a border portion of the integrated circuit.

22. A mold according to Claim 19, wherein the insert comprises a cylindrical skirt connected to adjacent portions of the first half-mold, and an end carried by the cylindrical skirt.

23. A mold for molding a plastic protective package for encapsulating an integrated circuit that can be at least partially activated from outside of the protective package, the mold comprising:

first and second half-molds comprising metal and which are laid onto each other to form a space for containing the integrated circuit; and

an elastically deformable membrane connected to the first half-mold and projecting substantially towards the

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integrated circuit to abut in pressing contact against at least one portion of the integrated circuit during a molding phase;

said first half-mold having an opening therein communicating with a back face of said elastically deformable membrane and for connection to a pressure source.

24. A mold according to Claim 23, wherein the at least one portion comprises a border portion of the integrated circuit.

25. A mold according to Claim 23, wherein said elastically deformable membrane comprises a cylindrical skirt connected to adjacent portions of the first half-mold, and an end carried by the cylindrical skirt.

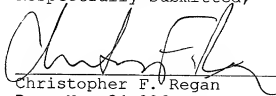
REMARKS

It is believed that all of the claims are patentable over the prior art. For better readability and the Examiner's convenience, the newly submitted claims differ from the translated counterpart claims, which are being canceled. The newly submitted claims do not represent changes or amendments that narrow the claim scope for any reason related to the statutory requirements for patentability. Accordingly, after the Examiner completes a thorough examination and finds the claims patentable, a Notice of Allowance is respectfully requested in due course. Should the Examiner determine any

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minor informalities that need to be addressed, he is encouraged to contact the undersigned attorney at the telephone number below.

Respectfully submitted,



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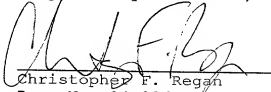
SUBMISSION OF PROPOSED DRAWING MODIFICATIONS

Director, U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Submitted herewith is a request for proposed drawing modifications as indicated in red ink to label FIGS. 1-6 as prior art, to draw a line for reference number 13 in FIG. 7 and to label reference number 13 in FIG. 8.

Respectfully submitted,



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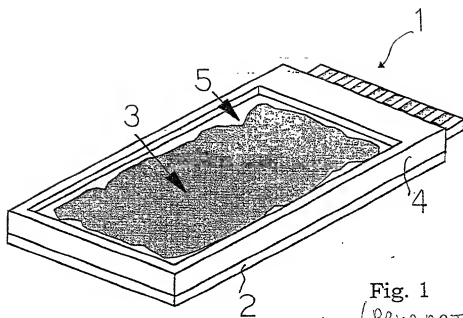


Fig. 1
(PRIOR ART)

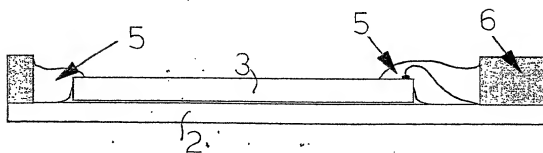


Fig. 2
(PRIOR ART)

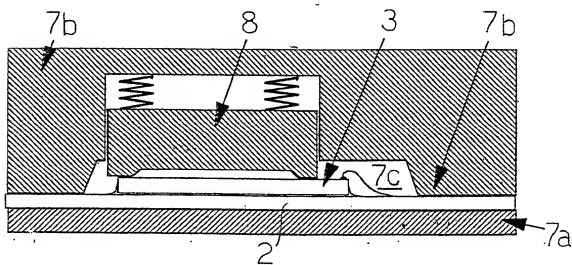


Fig. 3
(PRIOR ART)

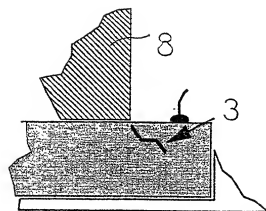


Fig. 4
(PRIOR ART)

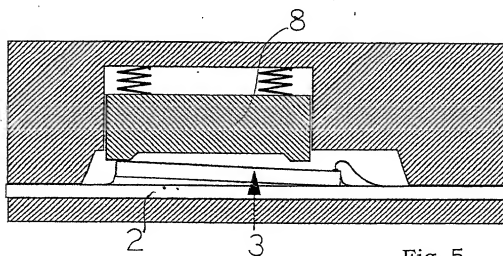


Fig. 5
(PRIOR ART)

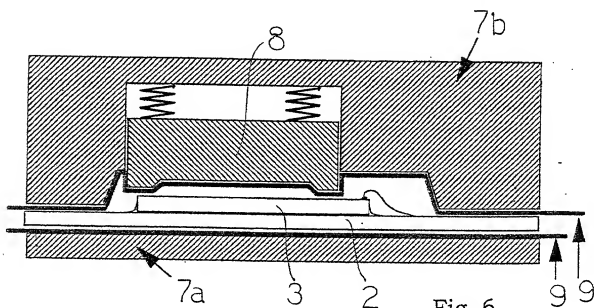


Fig. 6
(PRIOR ART)

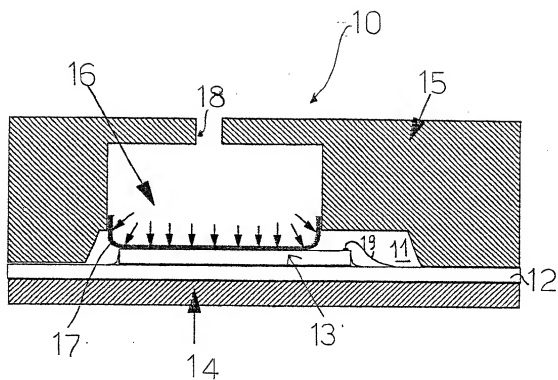


Fig. 7

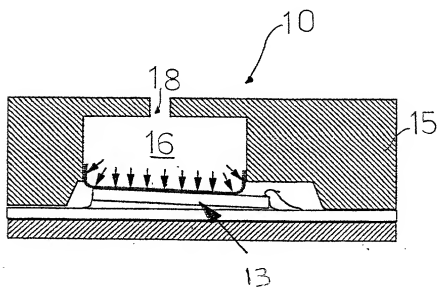


Fig. 8